

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC109N10NS3 G	**Issued**	11. November 2019
MA#	MA001617550		
Package	PG-TDSON-8-39	**Weight***	113.03 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.461	2.18	2.18	21772	21772
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.048	0.04		428	
	non noble metal	copper	7440-50-8	48.352	42.80	42.85	427789	428346
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	540	540
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		721	
	plastics	epoxy resin	-	6.437	5.69		56946	
	inorganic material	silicondioxide	60676-86-0	34.219	30.28	36.04	302751	360418
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13448	13448
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1402	1402
solder	non noble metal	tin	7440-31-5	0.046	0.04		406	
	noble metal	silver	7440-22-4	0.057	0.05		508	
	non noble metal	lead	7439-92-1	2.192	1.94	2.03	19396	20310
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.150	0.13		1327	
	non noble metal	copper	7440-50-8	16.910	14.96	15.11	149609	151131
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2629	2633
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com